

ABSTRACT OF THE DISCLOSURE

A tape ball grid array package and a method of fabricating the package. A dielectric tape having a metallic layer on both sides is provided. The metallic layers are patterned to form circuits. A plurality of via holes is formed in the dielectric tape. The via holes pass

5 through the lower metallic layer and the tape dielectric but stop at the upper metallic layer, thereby forming a plurality of blind holes. A solder mask layer is formed over each side of the tape and the solder mask layers are patterned to expose a portion of the metallic layer serving as contact points for connecting with a chip. A solder ball is inserted into each blind hole. One end of the solder ball protrudes from the surface of the solder mask layer. Wire-bonding operation or flip-chip assembly process is conducted to form electrical connection
10 between the chip and the contact points.

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 25 26 27 28 29 30 31 32 33 34 35 36 37 38 39 40 41 42 43 44 45 46 47 48 49 50 51 52 53 54 55 56 57 58 59 60 61 62 63 64 65 66 67 68 69 70 71 72 73 74 75 76 77 78 79 80 81 82 83 84 85 86 87 88 89 90 91 92 93 94 95 96 97 98 99 100